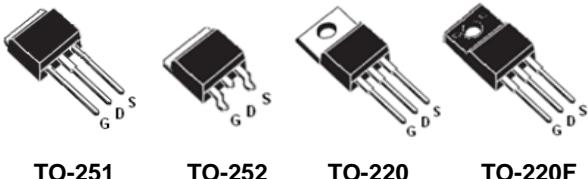
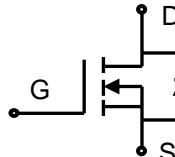


Lonten N-channel 650V, 2A Power MOSFET

Description	Product Summary
The Power MOSFET is fabricated using the advanced planer VDMOS technology. The resulting device has low conduction resistance, superior switching performance and high avalanche energy.	V_{DSS} 650V I_D 2A $R_{DS(on),max}$ 5.2Ω $Q_{g,typ}$ 10.2 nC
Features	
<ul style="list-style-type: none"> ◆ Low $R_{DS(on)}$ ◆ Low gate charge (typ. $Q_g = 10.2$ nC) ◆ 100% UIS tested ◆ RoHS compliant 	
Applications	  N-Channel MOSFET
	

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	650	V
Continuous drain current ($T_c = 25^\circ\text{C}$) ($T_c = 100^\circ\text{C}$)	I_D	2 1.3	A A
Pulsed drain current ¹⁾	I_{DM}	8	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ²⁾	E_{AS}	80	mJ
Peak diode recovery dv/dt ³⁾	dv/dt	5	V/ns
Power Dissipation TO-220F ($T_c = 25^\circ\text{C}$) Derate above 25°C	P_D	27 0.22	W W/ $^\circ\text{C}$
Power Dissipation TO-220\ TO-251\ TO-252 ($T_c = 25^\circ\text{C}$) Derate above 25°C		35 0.28	W W/ $^\circ\text{C}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$
Continuous diode forward current	I_S	2	A
Diode pulse current	$I_{S,pulse}$	8	A

Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO-220F	TO-220\TO-251\TO-252	
Thermal resistance, Junction-to-case	$R_{\theta JC}$	4.63	3.57	$^\circ\text{C/W}$
Thermal resistance, Junction-to-ambient	$R_{\theta JA}$	100	62	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube	Units/Real
LNC2N65	TO-220	LNC2N65	50	
LND2N65	TO-220F	LND2N65	50	
LNG2N65	TO-252	LNG2N65		3000
LNH2N65	TO-251	LNH2N65	80	

Electrical Characteristics

$T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=0.25 \text{ mA}$	650	-	-	V
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=0.25 \text{ mA}$	2	-	4	V
Drain cut-off current	I_{DSS}	$V_{\text{DS}}=650 \text{ V}, V_{\text{GS}}=0 \text{ V},$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	-	-	1 100	μA
Gate leakage current, Forward	I_{GSSF}	$V_{\text{GS}}=30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{\text{GS}}=-30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=1 \text{ A}$	-	4.2	5.2	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}} = 25 \text{ V}, V_{\text{GS}} = 0 \text{ V},$ $f = 1 \text{ MHz}$	-	338	-	pF
Output capacitance	C_{oss}		-	36	-	
Reverse transfer capacitance	C_{rss}		-	3.4	-	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 325 \text{ V}, I_{\text{D}} = 2 \text{ A}$ $R_G = 10 \Omega, V_{\text{GS}}=15 \text{ V}$	-	17.2	-	ns
Rise time	t_r		-	35.6	-	
Turn-off delay time	$t_{\text{d(off)}}$		-	33.9	-	
Fall time	t_f		-	29	-	
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{\text{DD}}=520 \text{ V}, I_{\text{D}}=2 \text{ A},$ $V_{\text{GS}}=0 \text{ to } 10 \text{ V}$	-	2.6	-	nC
Gate to drain charge	Q_{gd}		-	4.7	-	
Gate charge total	Q_g		-	10.2	-	
Gate plateau voltage	V_{plateau}		-	5	-	
Reverse diode characteristics						
Diode forward voltage	V_{SD}	$V_{\text{GS}}=0 \text{ V}, I_{\text{F}}=2 \text{ A}$	-	-	1.5	V
Reverse recovery time	t_r	$V_R=400 \text{ V}, I_{\text{F}}=2 \text{ A},$ $dI_{\text{F}}/dt=100 \text{ A}/\mu\text{s}$	-	221.8	-	ns
Reverse recovery charge	Q_{rr}		-	0.75	-	
Peak reverse recovery current	I_{rrm}		-	7.4	-	

Notes:

1. Pulse width limited by maximum junction temperature.
2. $L=10\text{mH}$, $I_{\text{AS}} = 4\text{A}$, Starting $T_j = 25^\circ\text{C}$.
3. $I_{\text{SD}} = 2\text{A}$, $di/dt \leq 100\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq \text{BV}_{\text{DS}}$, Starting $T_j = 25^\circ\text{C}$.

Electrical Characteristics Diagrams

Figure 1. Typical Output Characteristics

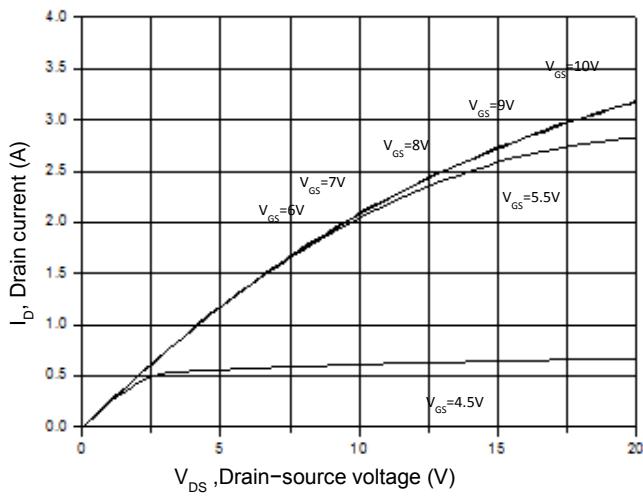


Figure 2. Transfer Characteristics

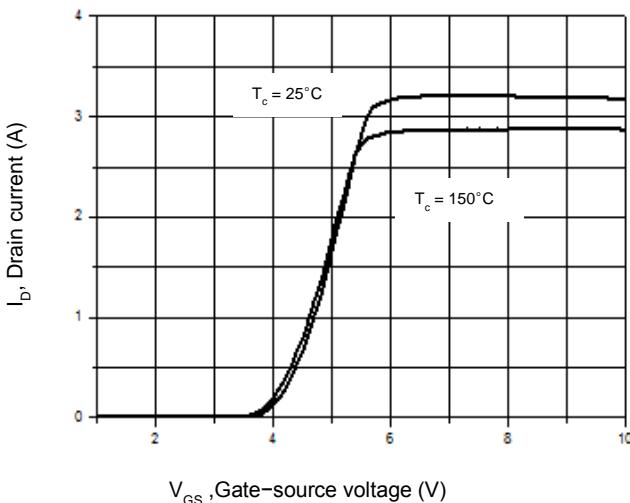


Figure 3. On-Resistance Variation vs. Drain Current

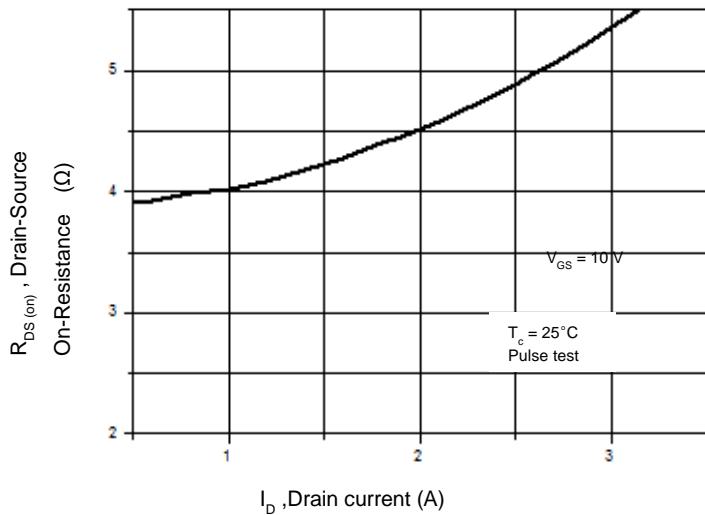


Figure 4. Threshold Voltage vs. Temperature

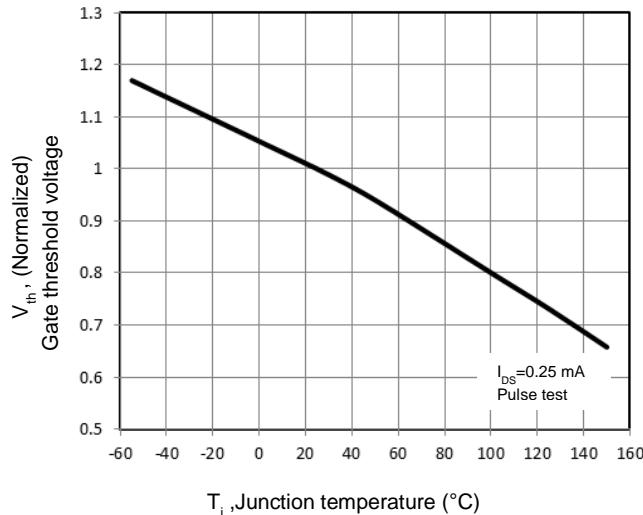


Figure 5. Breakdown Voltage vs. Temperature

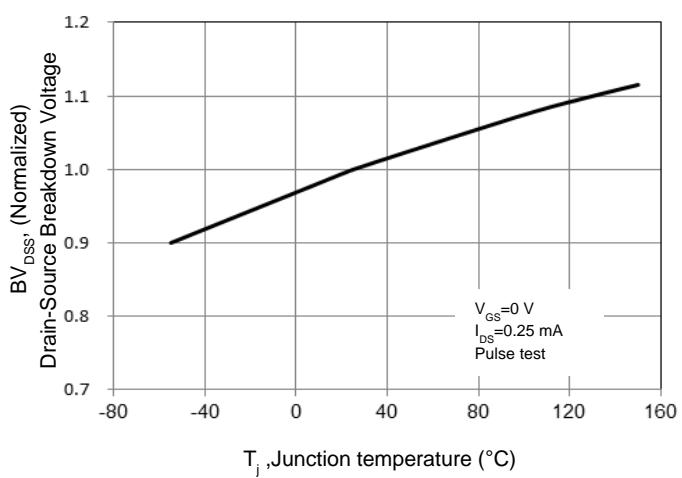


Figure 6. On-Resistance vs. Temperature

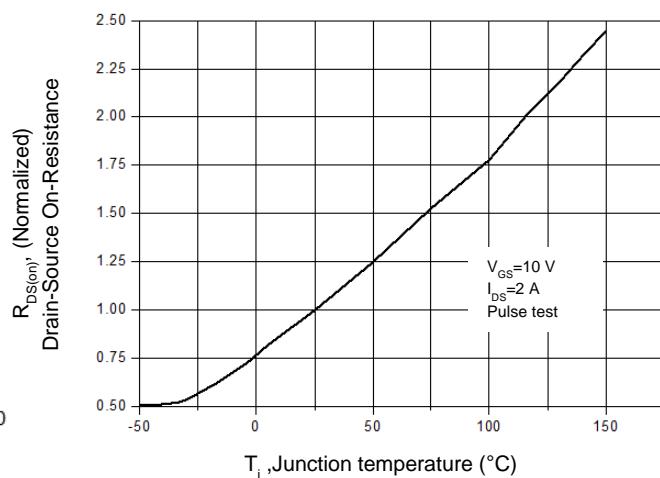


Figure 7. Capacitance Characteristics

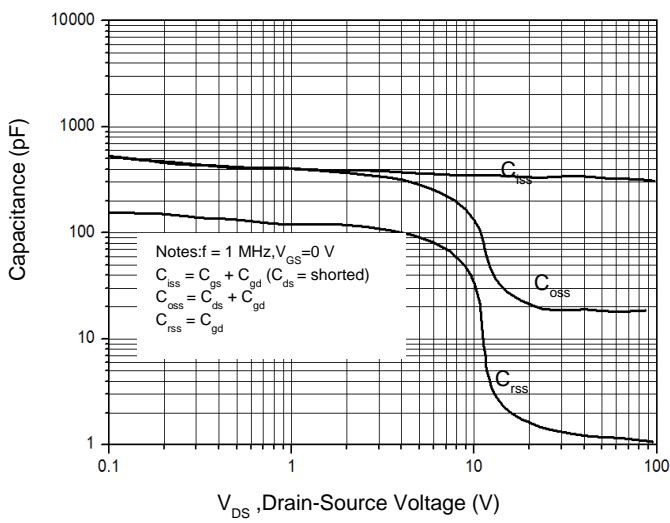


Figure 9. Maximum Safe Operating Area
TO-220F

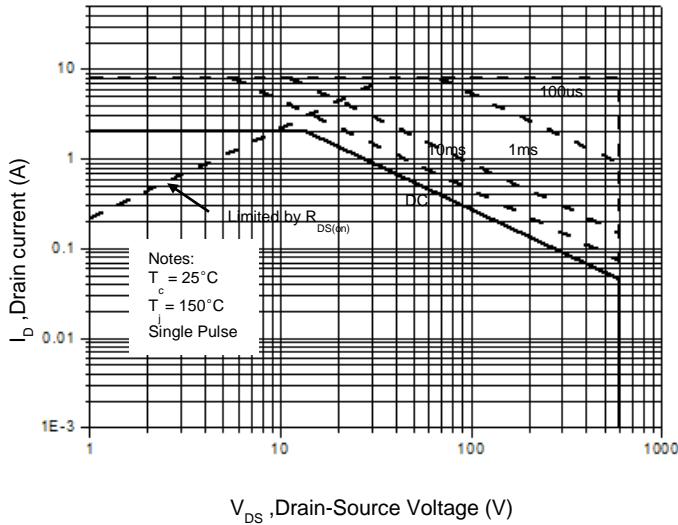


Figure 11. Power Dissipation vs. Temperature
TO-220F

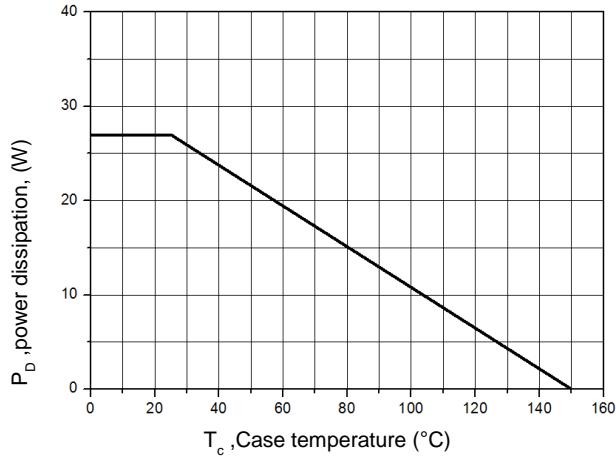


Figure 8. Gate Charge Characterist

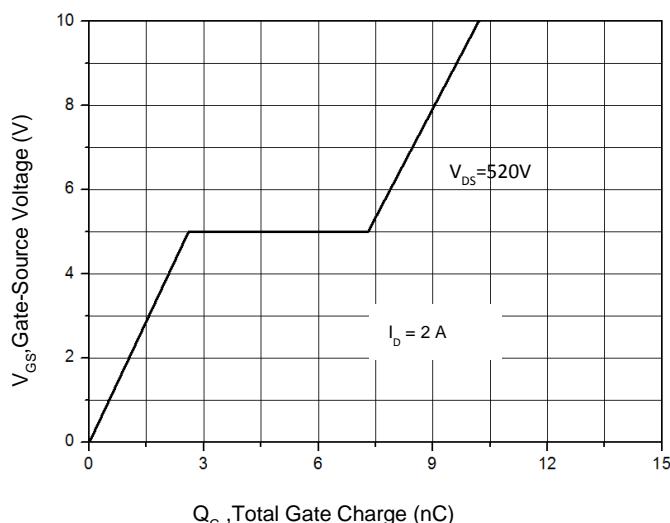


Figure 10. Maximum Safe Operating Area
TO-220/ TO-251/TO-252

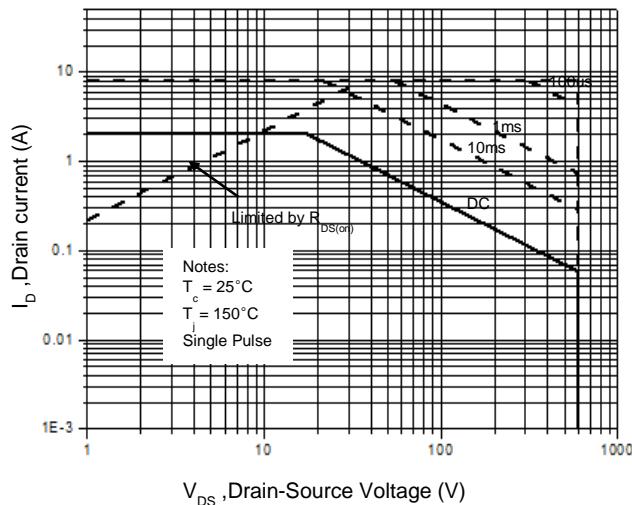


Figure 12. Power Dissipation vs. Temperature
TO-220/ TO-251/TO-252

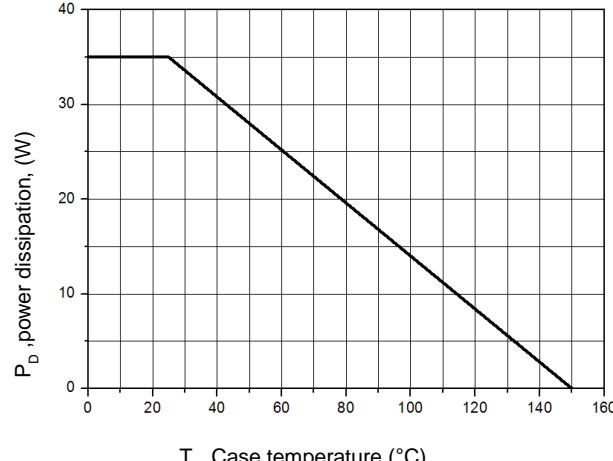


Figure 13. Continuous Drain Current vs. Temperature

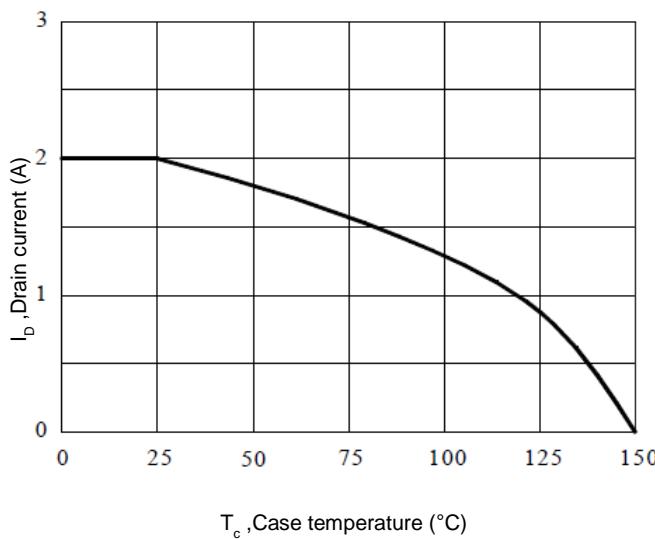


Figure 14. Body Diode Transfer Characteristics

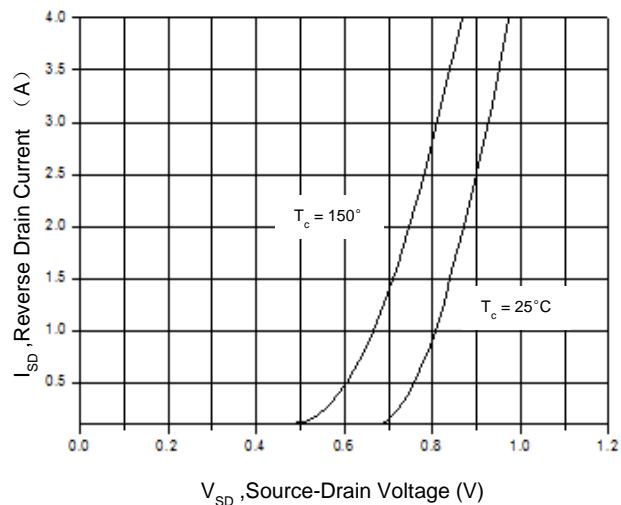


Figure 15 Transient Thermal Impedance, Junction to Case, TO-220F

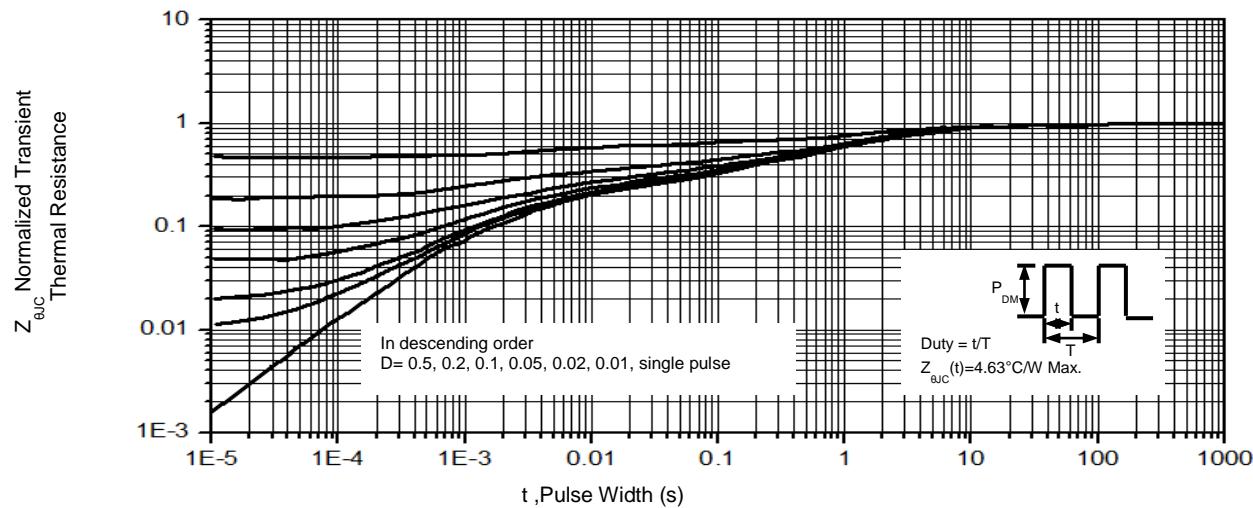
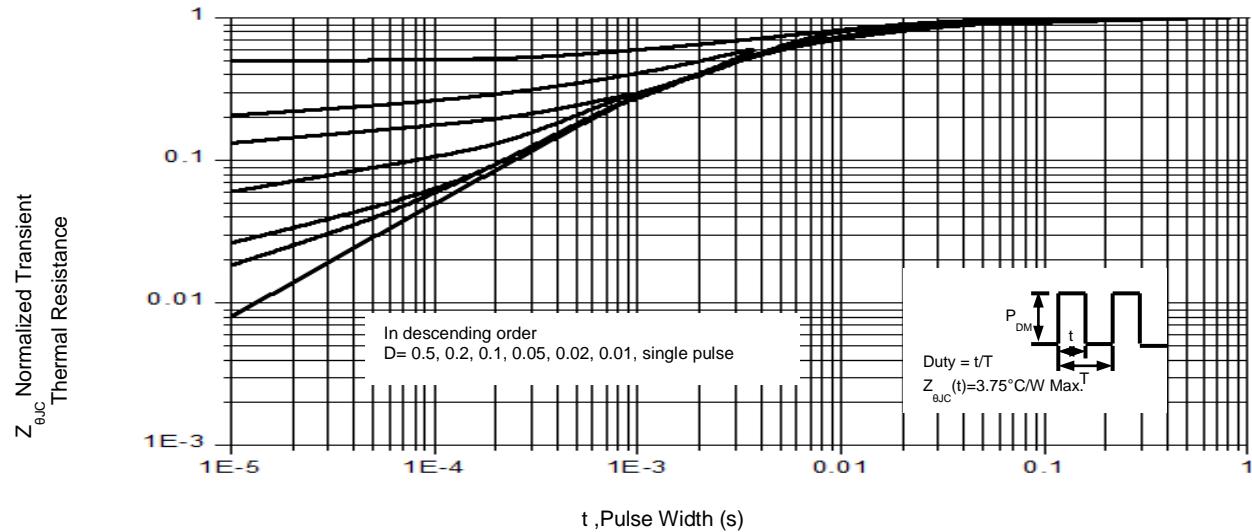
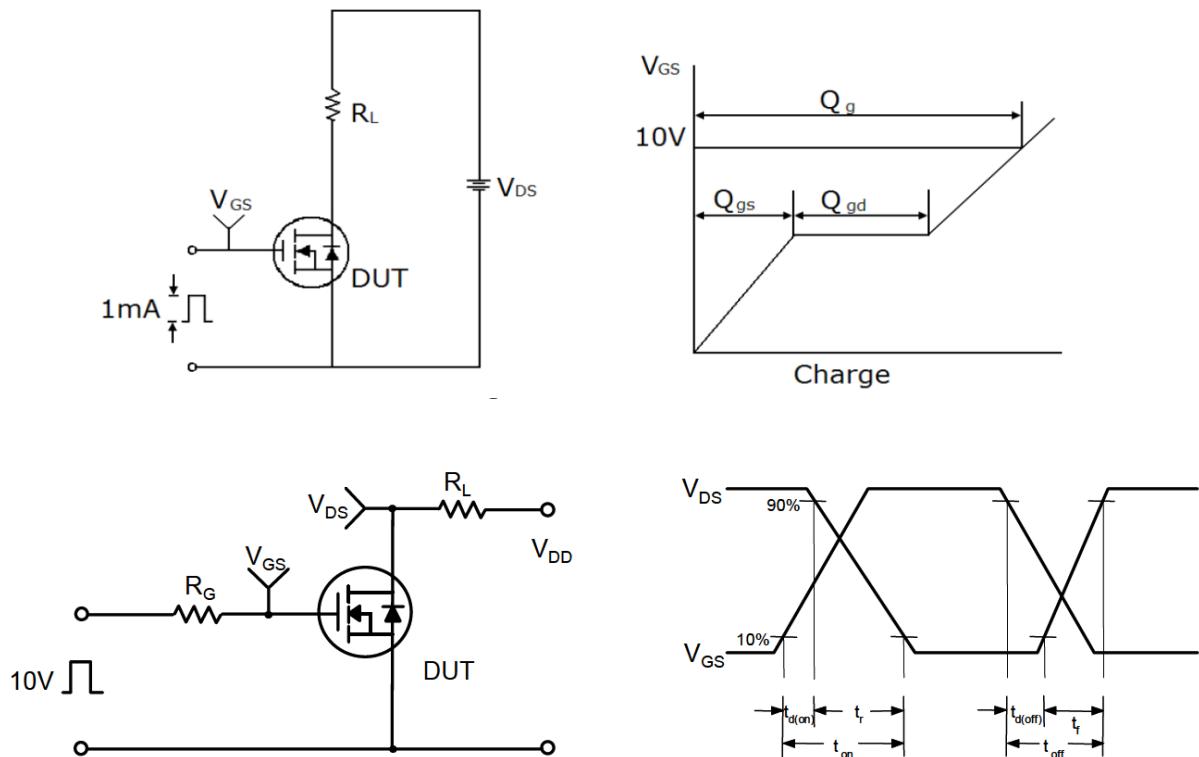


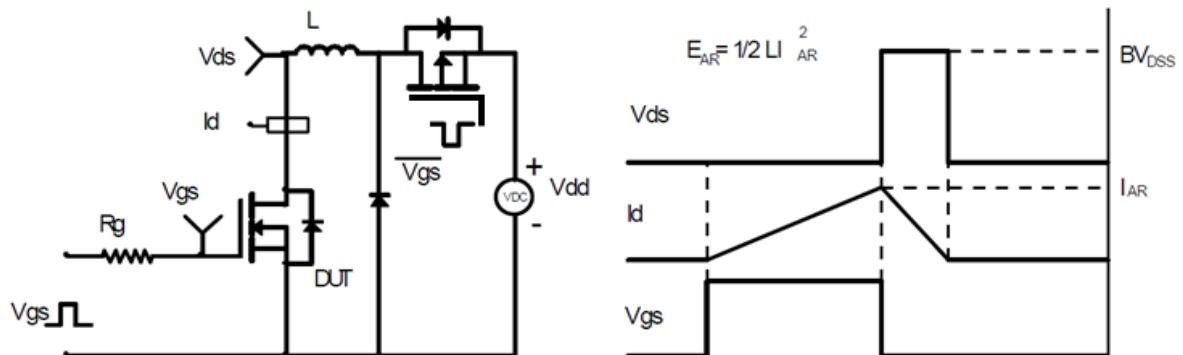
Figure 16. Transient Thermal Impedance, Junction to Case, TO-220/ TO-251/TO-252



Gate Charge Test Circuit & Waveform



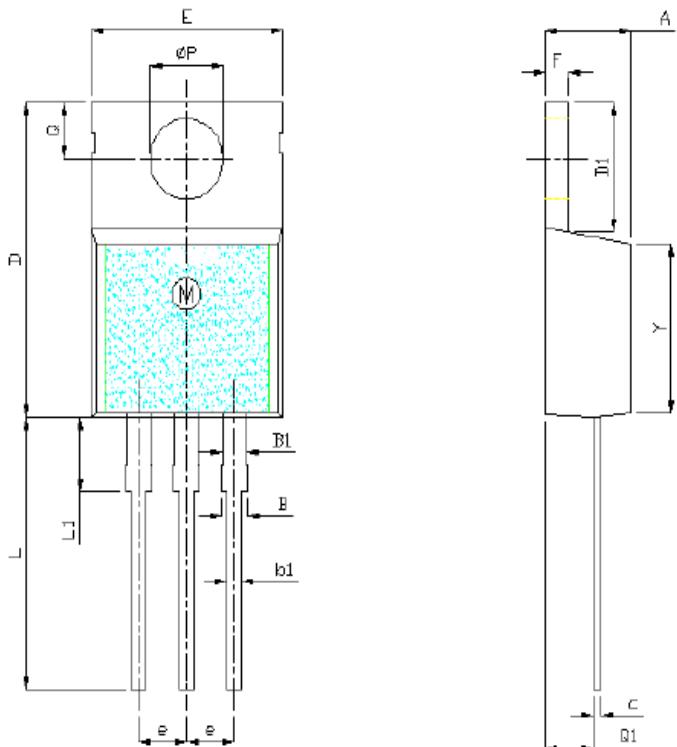
Unclamped Inductive Switching Test Circuit & Waveforms



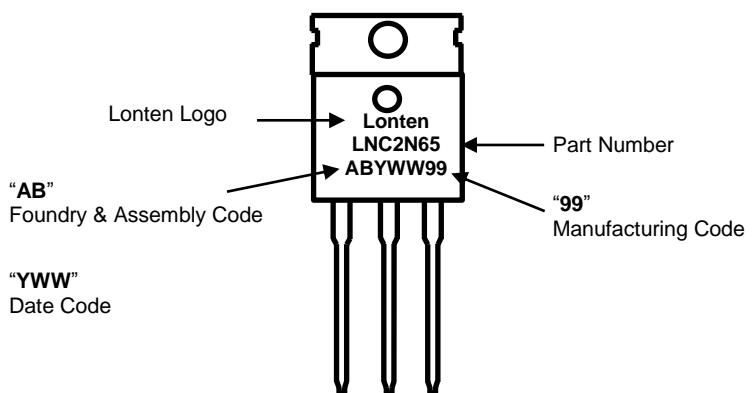
Mechanical Dimensions for TO-220

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	4		4.8	e	2.44	2.54	2.64
B	1.2		1.4	F	1.1		1.4
B1	1		1.4	L	12.5		14.5
b1	0.75		0.95	L1	3	3.5	4
c	0.4		0.55	ΦP	3.7	3.8	3.9
D	15		16.5	Q	2.5		3
D1	5.9		6.9	Q1	2		2.9
E	9.9		10.7	Y	8.02	8.12	8.22



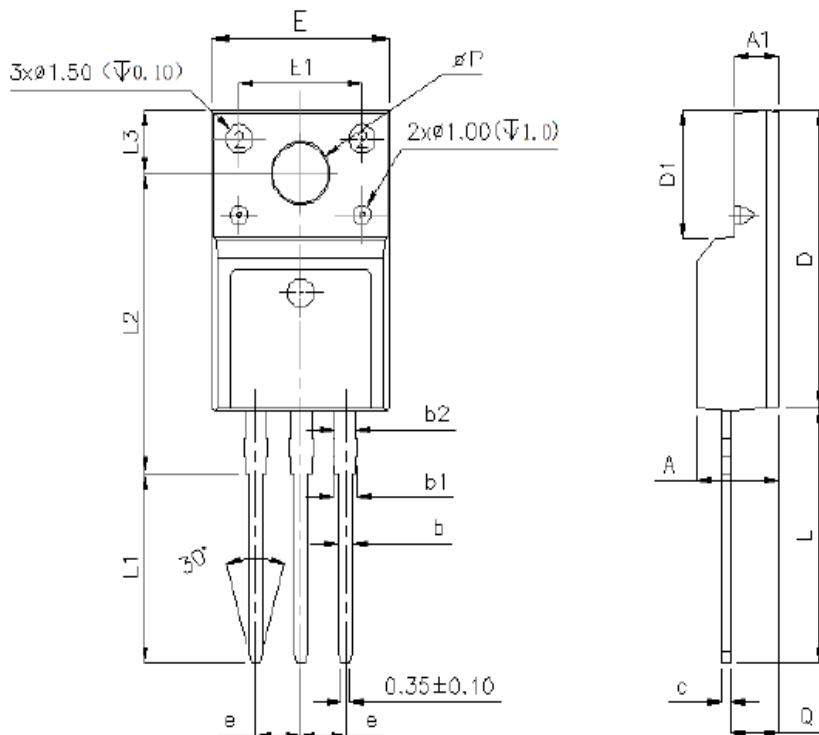
TO-220 Part Marking Information



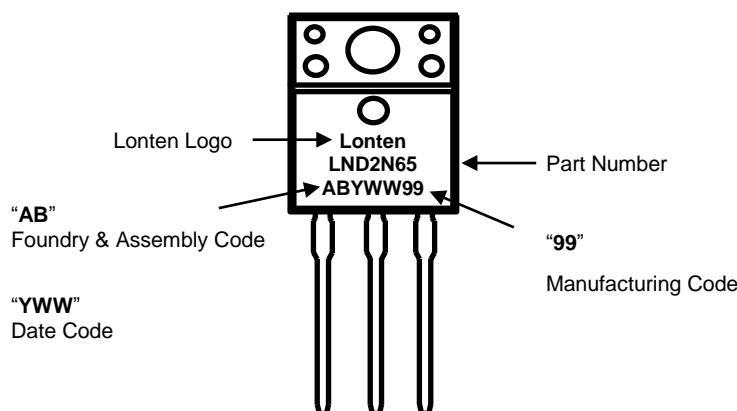
Mechanical Dimensions for TO-220F

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	4.5		4.9	E1	6.5	7	7.5
A1	2.3		2.9	e	2.44	2.54	2.64
b	0.65		0.9	L	12.5		14.3
b1	1.1		1.7	L1	9.45		10.05
b2	1.2		1.4	L2	15		16
c	0.35		0.65	L3	3.2		4.4
D	14.5		16.5	ΦP	3		3.3
D1	6.1		6.9	Ø	2.5		2.9
E	9.6		10.3				



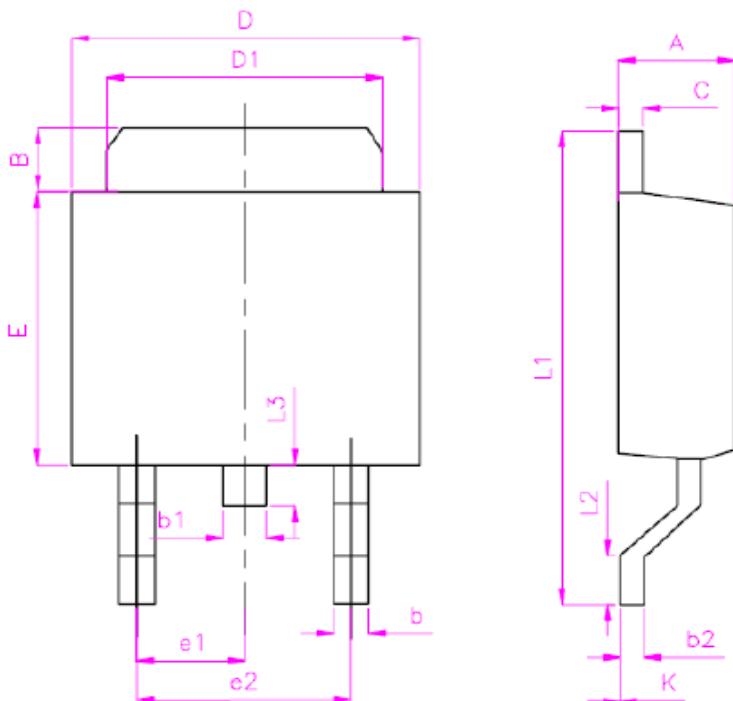
TO-220F Part Marking Information



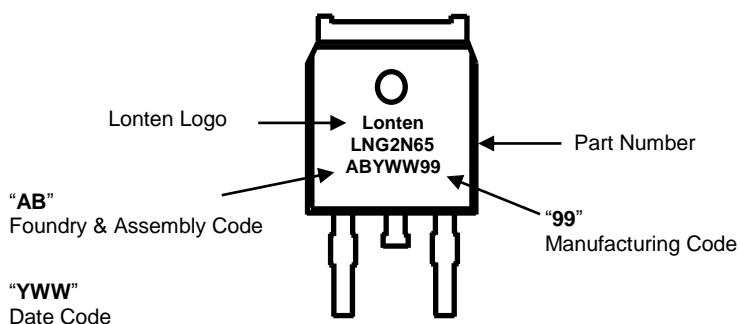
Mechanical Dimensions for TO-252

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	2.10		2.50	E	5.80		6.30
B	0.80		1.25	e1	2.25	2.30	2.35
b	0.50		0.85	e2	4.45		4.75
b1	0.50		0.90	L1	9.50		10.20
b2	0.45		0.60	L2	0.90		1.45
c	0.45		0.60	L3	0.60		1.10
D	6.35		6.75	K	-0.1		0.10
D1	5.10		5.50				



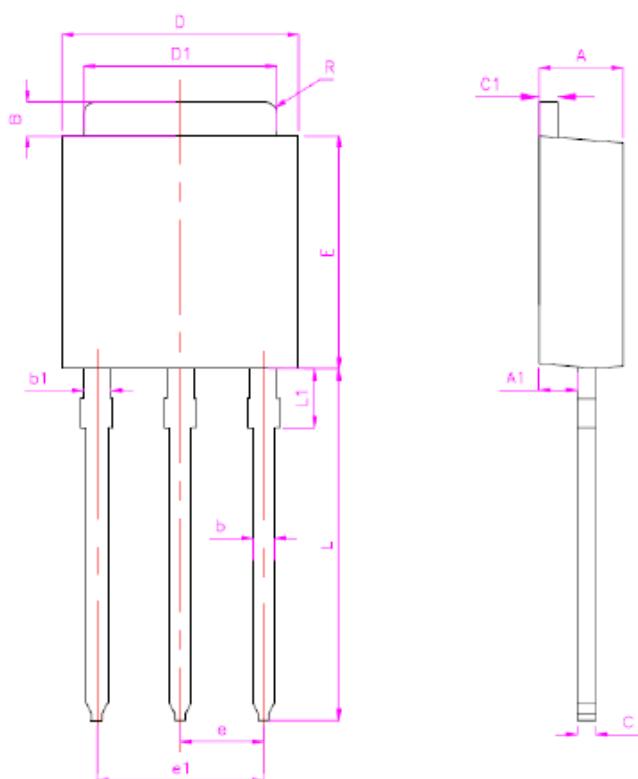
TO-252 Part Marking Information



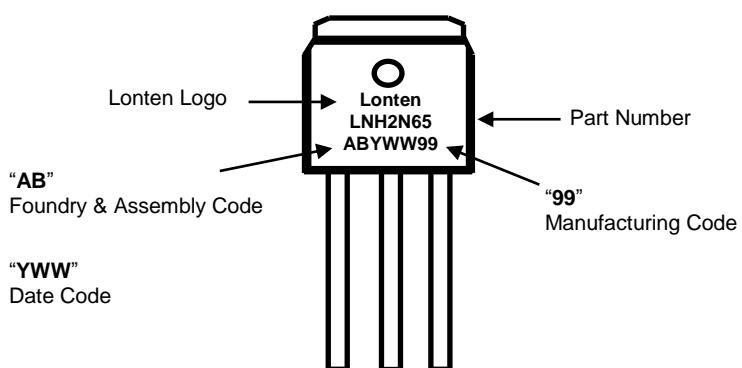
Mechanical Dimensions for TO-251

UNIT: mm

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	2.10		2.50	D1	5.10		5.50
A1	0.95		1.30	E	5.80		6.30
B	0.80		1.25	e	2.25	2.30	2.35
b	0.50		0.80	L	7.70		8.50
b1	0.70		0.90	L1	1.45		1.95
C	0.45		0.60	R		0.30	
C1	0.45		0.60				
D	6.35		6.75				



TO-251 Part Marking Information



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